

## SANYO Semiconductors

# DATA SHEET



## N-Channel Silicon MOSFET MCH3479 — General-Purpose Switching Device **Applications**

### **Features**

- ON-resistance  $R_{DS}(on)1=49m\Omega$  (typ.)
- 1.8V drive
- · Halogen free compliance
- Protection diode in

## **Specifications**

#### Absolute Maximum Ratings at Ta=25°C

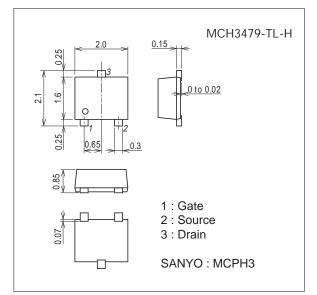
	-			
Parameter	Symbol	Conditions	Ratings	Unit
Drain-to-Source Voltage	VDSS		20	V
Gate-to-Source Voltage	VGSS		±12	V
Drain Current (DC)	ID		3.5	A
Drain Current (Pulse)	IDP	PW≤10μs, duty cycle≤1%	14	A
Allowable Power Dissipation	PD	When mounted on ceramic substrate (900mm <sup>2</sup> ×0.8mm)	0.9	W
Channel Temperature	Tch		150	°C
Storage Temperature	Tstg		-55 to +150	°C

• Package

• JEITA, JEDEC

#### Package Dimensions

#### unit : mm (typ) 7019A-003



#### Product & Package Information

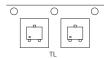
: MCPH3

: SC-70, SOT-323

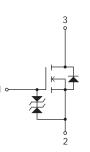
• Minimum Packing Quantity : 3,000 pcs./reel

#### Packing Type : TL

## Marking



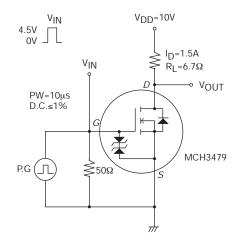
**Electrical Connection** 



### Electrical Characteristics at Ta=25°C

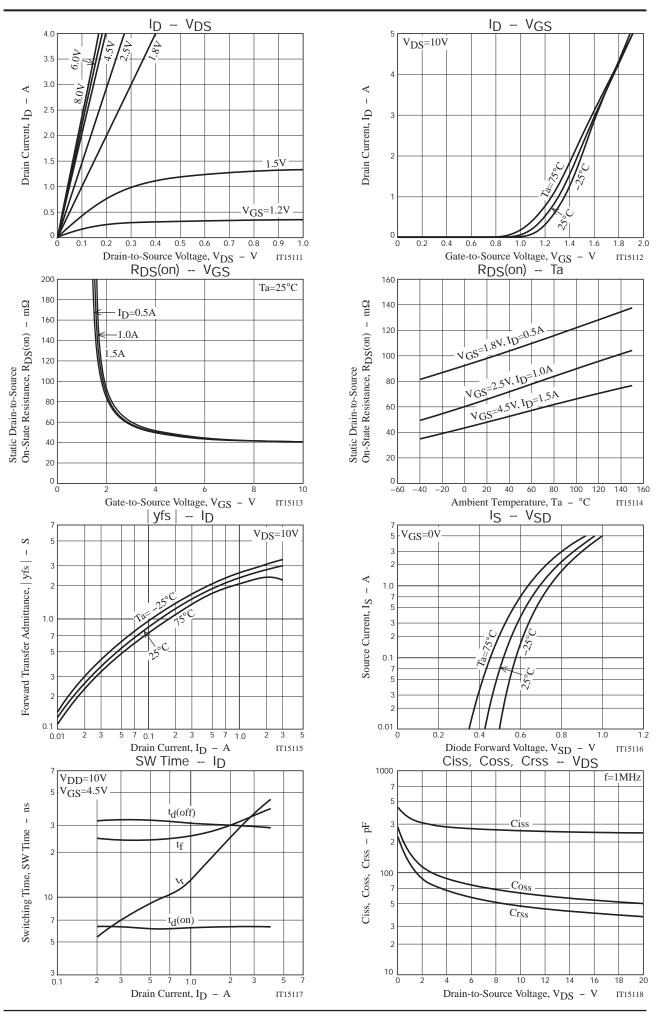
Deneration	Cumple al		Ratings				
Parameter	Symbol	Conditions	min	typ	max	Unit	
Drain-to-Source Breakdown Voltage	V(BR)DSS	ID=1mA, VGS=0V	20			V	
Zero-Gate Voltage Drain Current	IDSS	V <sub>DS</sub> =20V, V <sub>GS</sub> =0V			1	μΑ	
Gate-to-Source Leakage Current	IGSS	V <sub>GS</sub> =±8V, V <sub>DS</sub> =0V			±10	μΑ	
Cutoff Voltage	V <sub>GS</sub> (off)	V <sub>DS</sub> =10V, I <sub>D</sub> =1mA	0.4		1.3	V	
Forward Transfer Admittance	yfs	V <sub>DS</sub> =10V, I <sub>D</sub> =1.5A		2.8		S	
	R <sub>DS</sub> (on)1	ID=1.5A, VGS=4.5V		49	64	mΩ	
Static Drain-to-Source On-State Resistance	R <sub>DS</sub> (on)2	ID=1A, VGS=2.5V		68	95	mΩ	
	R <sub>DS</sub> (on)3	ID=0.5A, VGS=1.8V		99	149	mΩ	
Input Capacitance	Ciss			260		pF	
Output Capacitance	Coss	V <sub>DS</sub> =10V, f=1MHz		65		pF	
Reverse Transfer Capacitance	Crss			50		pF	
Turn-ON Delay Time	t <sub>d</sub> (on)			6.2		ns	
Rise Time	tr			19		ns	
Turn-OFF Delay Time	td(off)	See specified Test Circuit.		30		ns	
Fall Time	tf			28		ns	
Total Gate Charge	Qg			2.8		nC	
Gate-to-Source Charge	Qgs	V <sub>DS</sub> =10V, V <sub>GS</sub> =4.5V, I <sub>D</sub> =3.5A		0.6		nC	
Gate-to-Drain "Miller" Charge	Qgd	1		0.9		nC	
Diode Forward Voltage	V <sub>SD</sub>	IS=3.5A, VGS=0V		0.85	1.2	V	

## Switching Time Test Circuit

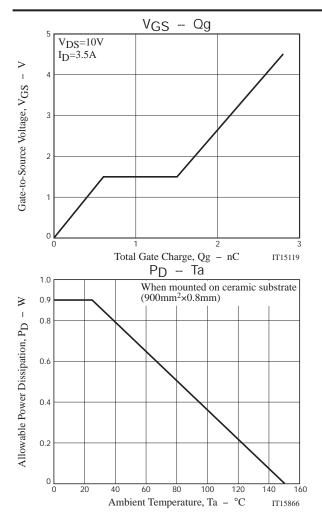


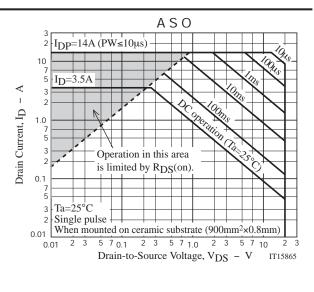
### **Ordering Information**

Device	Package	Shipping	memo	
MCH3479-TL-H	MCPH3	3,000pcs./reel	Pb Free and Halogen Free	



MCH3479





### Taping Specification MCH3479-TL-H

1. Packing Format

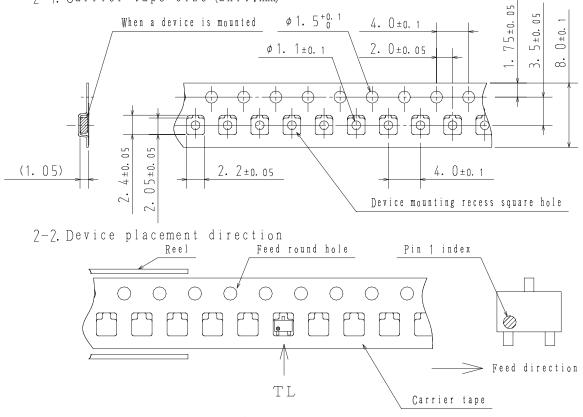
Packing method (unified filling) The form of a label may change in physical distribution process.   Image: Structure filling fill			mun Number of s contained (pcs)		Packing format		
Michael Michael Dimensions:mm (external) Dimensions:mm (external)   Packing method Reel label, Inner box label Quart is mm) Quart is mm)   Image: Comparison of the compa		Туре	Reel	Inner box	Outer box	Inner BOX (C-1) Outer BOX (A-7)	
Packing method Dimensions:mm (external) Dimensions:mm (external)   Packing method Reel label, Inner box label Quart itym   Image: Construction of the terminal is lead free. Image: Construction of the terminal is lead free.	МСРН 3	MCPH3	3,000	15,000	90,000	5 reels contained 6 inner boxes contained	
Packing method Reel label, Inner box label (unit:mm) Outer box label It is a label at the time of factory shipments. The form of a label may change in physical distribution process.						Dimensions:mm (external) Dimensions:mm (external)	
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Type No. Image: Constraint of the surface treatment of the terminal is lead free.	0	<		<	6	<u>59</u>	
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LEAD FREE 4

JEITA Phase 3

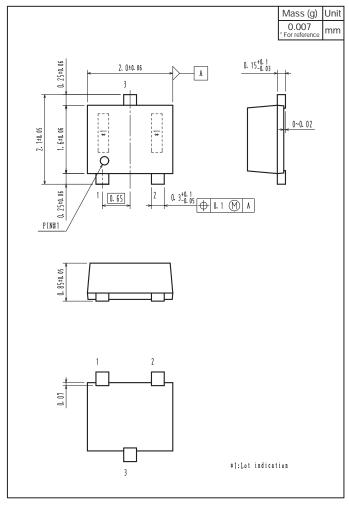
2. Taping configuration

2-1. Carrier tape size (unit:mm)

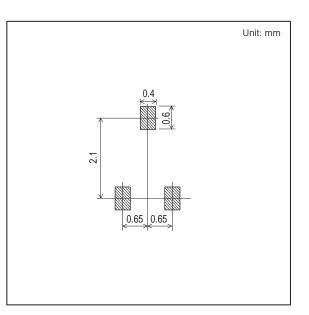


Those with pin 1 index on the feed hole side  $\cdots \cdots TL$ 

## Outline Drawing MCH3479-TL-H



## Land Pattern Example



## Note on usage : Since the MCH3479 is a MOSFET product, please avoid using this device in the vicinity of highly charged objects.

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